



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

61-112-57
Ca
9-12-02

In re the Application of:

Coyle, et al.

Docket No.: TI-31794

Serial No.: 09/992,387

Examiner: Lewis, M.

Filed: 11/16/01

Art Unit: 2822

For: FLIP-CHIP ON FILM ASSEMBLY FOR BALL GRID ARRAY PACKAGES

INFORMATION DISCLOSURE STATEMENT

TECHNOLOGY CENTER 2800

SEP -9 2002

RECEIVED

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

<p>MAILING CERTIFICATE</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.</p> <p><u>8-27-02</u></p> <p>Date</p> <p><u>Marianna Smith</u></p> <p>Marianna Smith</p>

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. They were cited in a corresponding European patent application. Copies of the listed references and European search report are enclosed. Please charge the \$180.00 fee to Deposit Account No. 20-0668.

Respectfully submitted,

Michael K. Skrehot
Attorney for Applicants
Reg. No. 36,682

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653
FAX: (972) 917-4418
(972) 917-4417

9/05/2002 DTESSEN1 00000063 200668 09992387

FC:126 180.00 CH